

SMT Assembly Capability CCI

Criteria	Specification
PCB Dimension (minimum)	L 50mm x W 50mm [L 2in x W 2in]
PCB Dimension (maximum)	L 510mm x W 460mm [L 20in x W 18in]
PCB Thickness	≤ 8mm [≤ 0.31in]
PCB Type	Rigid Flex Rigid-Flex Metal Core
Support Component	Surface-mount Device (SMD / SMT) Pin Through-hole (PTH)
Assembly Placement	Single side Double side
SMT Placement accuracy (Cpk≥1)	≥ 99.7% Process Yield
Chip	±40 µm
QFP ≤ 12mm x 12mm [≤ 0.47in x 0.47in]	±50 µm
QFP ≥ 12mm x 12mm and ≤ 32mm x 32mm [≥ 0.47in x 0.47in and ≤ 1.26in x 1.26in]	±30 µm
Placement Speed	35,800 Chip per Hour 22,000 Chip per Hour (IPC-9850)
Component dimension (minimum)	0402 Metric [01005 Imperial]
Component dimension (maximum)	L 150mm x W 25mm x H 28mm [L 5.9in x W 0.98in x H 1.1in]
SMT feeding package	Reel Cut Tape Tube Tray
Fiducials	Required
Solder Paste	SAC305 (IPC J-STD-006C)

	RoHS material only *Other material upon request
Solder Flux	ROLO (IPC J-STD-004B) No-clean only *Other material upon request
Halide Content	Halide Free IPC J-STD-004B
Halogen Content	Non-detectable (ND) at < 50 ppm JEITA ET-7304 (TM EN 14582) IEC 612249-2-21 (TM EN 14582) JEDEC (TM EN 14582)
Ag Chromate Test	Pass, No Halides present IPC J-STD-004B
Copper Mirror Test	Pass, Low activity, No corrosion IPC J-STD-004B
Copper Corrosion Test	Pass, Low activity, No corrosion IPC J-STD-004B
Electromigration	Pass Bellcore GR78 CORE Pass JIS-Z-3197-1999 8.5.4
Reflow Oven Maximum Gas Setpoint	350 °C [662 °F]
Gas Temperature Control Accuracy	± 1°C [± 1.8 °F]
Gas Thermal Uniformity	± 2°C [± 3.6 °F]
Soldering Iron Maximum Setpoint	450°C
Workmanship	IPC-A-610 Class 2 or 3 J-STD-001 Class 2 or 3